



DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = 25°C
	2.4Ω @ V _{GS} = 10V	510mA
60V	4.0Ω @ V _{GS} = 4V	390mA

Description and Applications

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Power management functions
- Analog Switch

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Up To 2kV
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.015 grams (approximate)

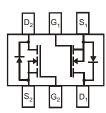




Top View

SOT26

Equivalent Circuit
Per Element



Top View Internal Schematic

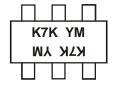
Ordering Information (Note 3)

Part Number	Case	Packaging
DMN601DMK-7	SOT26	3000/Tape & Reel

Notes:

- 1. No purposefully added lead
- 2. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com.
- 3. For packaging details, go to our website at http://www.diodes.com.

Marking Information



K7K = Marking Code YM = Date Code Marking Y = Year (ex: S = 2005) M = Month (ex: 9 = September)

Date Code Key

Year	2005	2006	2007	2008	2009	2010	2011	201	2 201	3 2014	2015	2016	2017
Code	S	T	U	V	W	Χ	Υ	Z	А	В	С	D	Е
Month	Jan	Feb	Mar	Apr	Ma	y Ju	un	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	(6	7	8	9	0	N	D



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V_{DSS}	60	V		
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current (Note 5) V 40V	Steady State	$T_A = 25$ °C $T_A = 70$ °C	I _D	510 400	mA
Continuous Drain Current (Note 5) V _{GS} = 10V	t<10s	$T_A = 25$ °C $T_A = 70$ °C	I _D	580 470	mA
Continuous Drain Current (Note 5) V	Steady State	T _A = 25°C T _A = 70°C	I _D	390 300	mA
Continuous Drain Current (Note 5) V _{GS} = 4V	t<10s	T _A = 25°C T _A = 70°C	I _D	440 340	mA
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	850	mA		
Maximum Body Diode Continuous Current	I _S	1.2	Α		

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Units	
Total Power Dissipation (Note 4)		P _D	0.7	W	
Thermal Decistance Junction to Ambient (Note 4)	Steady state	<u> </u>	157	°C/W	
Thermal Resistance, Junction to Ambient (Note 4)	t<10s	$R_{\theta JA}$	121		
Total Power Dissipation (Note 5)		PD	0.98	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	<u> </u>	113		
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	88	°C/W	
Thermal Resistance, Junction to Case (Note 5)		$R_{\theta JC}$	26		
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

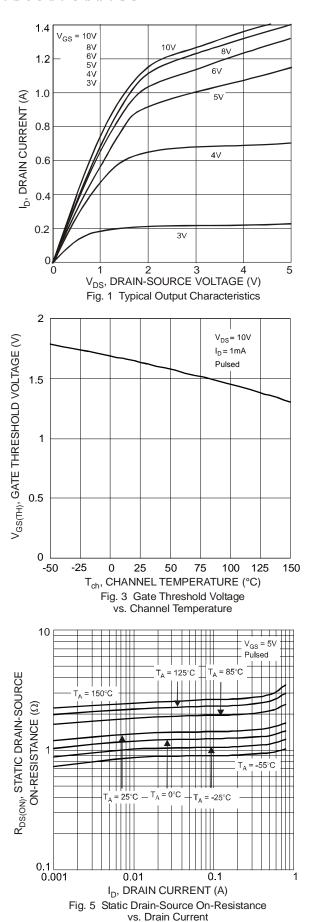
Electrical Characteristics @TA = 25°C unless otherwise specified

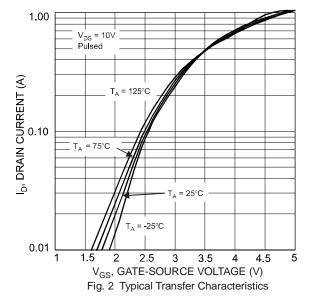
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	60	_		V	$V_{GS} = 0V, I_D = 10\mu A$
Zero Gate Voltage Drain Current	I _{DSS}			1	μА	$V_{DS} = 60V$, $V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}			±10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$V_{GS(th)}$	1.0	1.6	2.5	V	$V_{DS} = 10V, I_{D} = 1mA$
Static Drain-Source On-Resistance	D		_	2.4	Ω	$V_{GS} = 10V, I_D = 200mA$
Static Dialit-Source Off-Resistance		4.0	2.2	$V_{GS} = 4V, I_D = 200mA$		
Forward Transfer Admittance	Y _{fs}	100			ms	$V_{DS} = 10V, I_D = 200mA$
Diode Forward Voltage	V_{SD}	0.5	_	1.4	V	$V_{GS} = 0V, I_S = 115mA$
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	Ciss	_	30	50	pF	V/ 05V/ V/ 0V/
Output Capacitance	Coss		5	25	pF	$V_{DS} = 25V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	3	5.0	pF	1 = 1.0ivii iz
Gate Resistance	R_g	_	133	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge	Q_g	_	304	_		V 45V V 40V
Gate-Source Charge	Q_{gs}	_	84	_	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$
Gate-Drain Charge	Q_{gd}		203	_		$I_D = 250 \text{mA}$
Turn-On Delay Time	t _{D(on)}		3.9	_		
Turn-On Rise Time	t _r	_	3.4	_	ns	$V_{DS} = 30V, I_D = 0.2A,$
Turn-Off Delay Time	t _{D(off)}	_	15.7		115	$V_{GS} = 10V, R_G = 25\Omega, R_L = 150\Omega$
Turn-Off Fall Time	t _f		9.9	_		

Notes:

- 4. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate
 6. Short duration pulse test used to minimize self-heating effect
 7. Guaranteed by design. Not subject to production testing







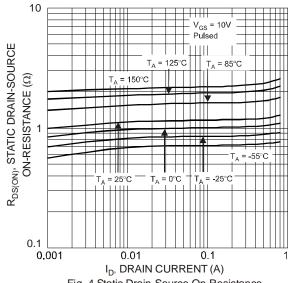


Fig. 4 Static Drain-Source On-Resistance vs. Drain Current

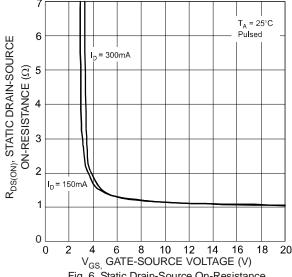


Fig. 6 Static Drain-Source On-Resistance vs. Gate-Source Voltage



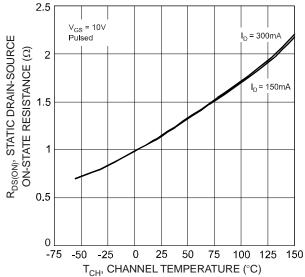


Fig. 7 Static Drain-Source On-State Resistance vs. Channel Temperature

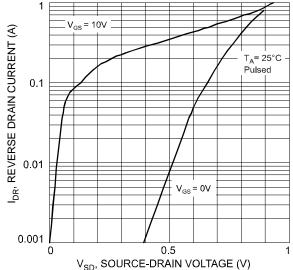


Fig. 9 Reverse Drain Current vs. Source-Drain Voltage

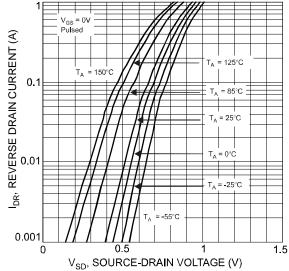


Fig. 8 Reverse Drain Current vs. Source-Drain Voltage

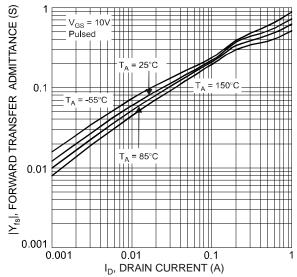
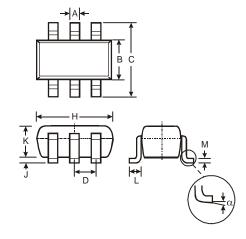


Fig.10 Forward Transfer Admittance vs. Drain Current

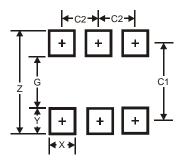
Package Outline Dimensions



SOT26								
Dim	Min	Max	Тур					
Α	0.35	0.50	0.38					
В	1.50	1.70	1.60					
O	2.70	3.00	2.80					
D	_	_	0.95					
Н	2.90	3.10	3.00					
7	0.013	0.10	0.05					
K	1.00	1.30	1.10					
L	0.35	0.55	0.40					
M	0.10	0.20	0.15					
α	0°	8°						
All D	imensi	ons in	mm					



Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.20
G	1.60
Х	0.55
Υ	0.80
C1	2.40
C2	0.95

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